

Prof. CQ Cui

Chairman, Technical program

ICEPT

Guangdong University of Technology

The 21st International Conference on Electronics Packaging Technology (ICEPT 2020) was held at the Conference Center of Guangzhou Science City from August 12<sup>th</sup> to 15<sup>th</sup>, 2020. The conference was hosted by Guangdong Greater Bay Area Institute of Integrated Circuit and System, Guangdong University of Technology (GDUT), IEEE Electronics Packaging Society, Electronic Manufacturing and Packaging Technology Society of the Chinese Institute of Electronics, organized by School of Electromechanical Engineering, Guangdong University of Technology / State Key Laboratory of Precision Electronic Manufacturing Technology and Equipment, and co-organized by National Center for Advanced Packaging (NCAP), State Key Laboratory of Mobile Network and Mobile Multimedia Technology (ZTE), Hong Kong Applied Science and Technology Research Institute Co. Ltd., Guangdong Fozhixin Microelectronics Technology Research Co., Ltd., Guangdong XH Microelectronics Co., Ltd., Guangzhou Semiconductor Industry Association, IEEE EPS Beijing Chapter and Beijing Faith Information Consultant Ltd. More than 600 delegates from China, the United States, Sweden, Singapore, Japan, Netherlands and many other countries and regions, including experts, scholars and business representatives participated in the event.



Welcome Speech from Prof. Tianchun Ye



Welcome Speech from Prof. Chris Bailey

At the opening ceremony, Prof. Tianchun Ye (Director of Institute of Microelectronics, CAS), Prof. Xin Chen (Director of State Key Laboratory of Precision Electronics Manufacturing Technology and Equipment, GDUT), Ms. Lulu He (Deputy Mayor of Huangpu District, Guangzhou), Mr. Haijun Zhao (Joint CEO of SMIC), and Prof. Chris Bailey (Chair of IEEE EPS, University of Greenwich) delivered welcome speeches. Prof. Chris Bailey (Chair of IEEE EPS, University of Greenwich), Mr. Lung Chu (President of SEMI China), Dr. Kayleen Helms (Intel), Prof. Johan Liu (Chalmers University of Technology, Shanghai University), Prof. Zhihua Wang (Tsinghua University), Prof. Kuochi Zhang (Delft University of Technology, The Netherlands), Prof. Xuejun Fan (Lamar University, USA), Dr. Farhang Yazdani (BroadPak, USA), Dr. William Chen (ASE Group), Prof. Fujiang Lin (University of Science and Technology of China), Prof. Sheng Liu, (Wuhan University), Dr. Akitsu Shigetou (National Institute of Materials Science of Japan) gave keynote speeches.



Plenary Speech from Prof. Xin Chen

The conference has received more than 420 papers from academia and industry around the world. Ten technical sessions have been held, including advanced

packaging, interconnect technology, packaging materials and processes, modeling and simulation, packaging equipment, quality and reliability, power electronics, optoelectronics and display, MEMS and fan-out packaging, and packaging in emerging fields. The conference presented more than one hundred speeches in the form of professional developing courses, keynote speeches, session keynote speeches, and oral presentations. 20 papers were awarded the ICEPT Outstanding Paper Award and ICEPT Best Student Paper Award respectively. 4 posters were awarded the ICEPT Outstanding Poster Award.

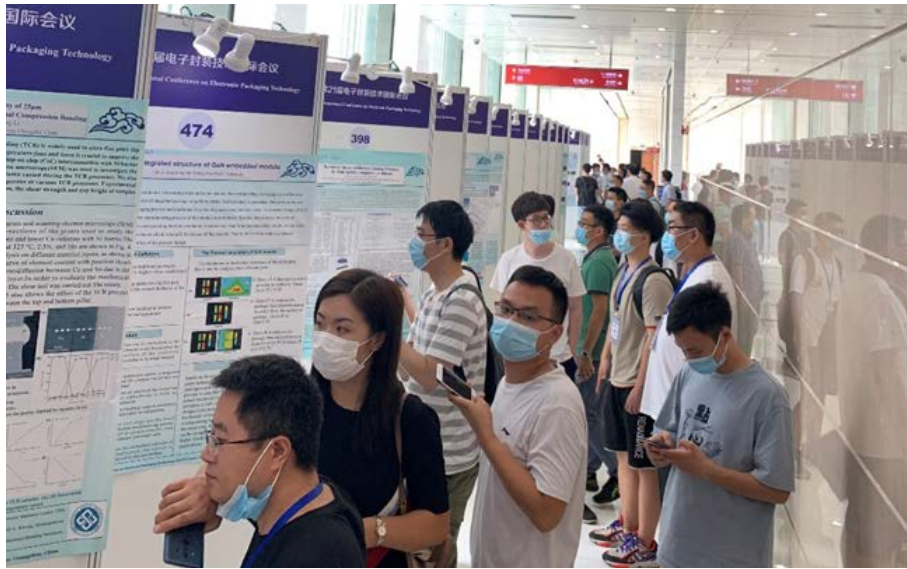


Professional Developing Course



Session keynote Speech





Poster presentation section



Audience of an Oral Section



Prof. Tianchun Ye and Authors of the Outstanding Papers



Prof. Sheng Liu, Prof. Jian Cai, and Authors of the Best Student Papers



Prof. Chengqiang Cui and Authors of the Outstanding Posters



Participants of ICEPT 2020 Conference

The delegates fully exchanged key technologies and latest progress in the field of electronic packaging technology. The conference played an important role in the training of high-end talents in electronic packaging in China and made special contributions to the technical exchange of the world electronic packaging industry.